



A Product Line of Diodes Incorporated

ZXTP25040DFL

40V PNP LOW POWER TRANSISTOR IN SOT23

#### Features

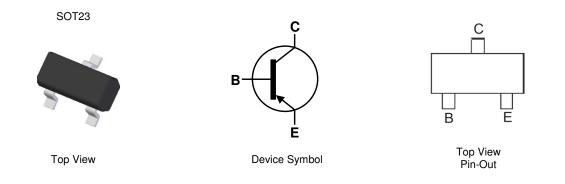
- BV<sub>CEO</sub> > -40V
- BV<sub>ECO</sub> > --3V
- I<sub>C</sub> = -1.5A Continuous Collector Current
- V<sub>CE(sat)</sub> < -115mV @ -1A</li>
- R<sub>CE(sat)</sub> = 82mΩ
- High Peak Current
- Complementary Part Number ZXTN25040DFL
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.008 grams (Approximate)

#### Applications

- MOSFET and IGBT Gate Driving
- DC-DC Converters



#### Ordering Information (Note 4)

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Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP25040DFLTA	1A2	7	8	3,000

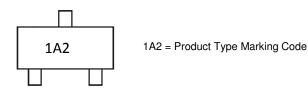
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

#### **Marking Information**





# Absolute Maximum Ratings (@ $T_A = +25 \,^{\circ}$ C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-45	V
Collector-Emitter Voltage (Forward Blocking)	V <sub>CEO</sub>	-40	V
Emitter-collector voltage (Reverse Blocking)	V <sub>ECO</sub>	-3	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current (Note 5)	lc	-1.5	A
Base Current	IB	-500	mA
Peak Pulse Current	Ісм	-5	A

#### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 5)	D	310	mW	
Fower Dissipation	(Note 6)	- P <sub>D</sub>	350	111VV	
Thermal Decistores, Junction to Ambient	(Note 5)	D	403	°C/W	
Thermal Resistance, Junction to Ambient	(Note 6)	- R <sub>0JA</sub>	357	-0/00	
Thermal Resistance, Junction to Leads (Note 7)		R <sub>0JL</sub>	350	°C/W	
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C	

## ESD Ratings (Note 8)

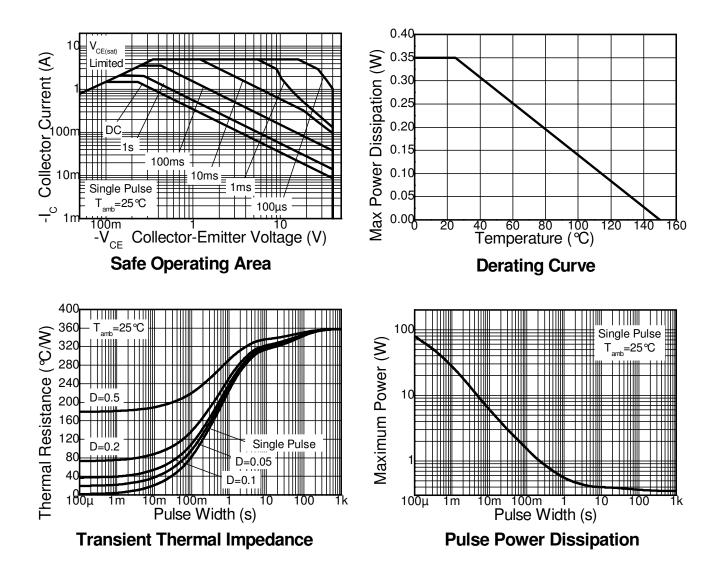
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes: 5. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

6. Same as Note 5, except the device is mounted on 15 mm x 15mm 1oz copper.
7. Thermal resistance from junction to solder-point (at the end of the leads).
8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



# Thermal Characteristics and Derating Information



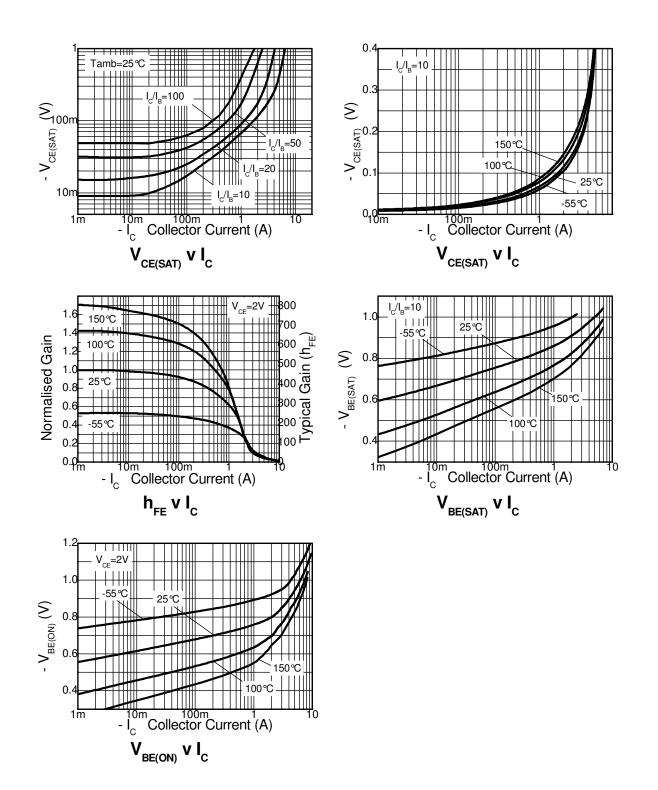


Electrical Characteristics (@T <sub>A</sub> = +23	5℃, unless otherwi	se specified	.)			
Characteristic	Symbol	Min	Тур	Мах	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-45	-75	-	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	-40	-65	-	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-8.2	-	V	I <sub>E</sub> = -100μA
Emitter-Base Breakdown Voltage	BV <sub>ECO</sub>	-3	-8.7	-	V	I <sub>E</sub> = -100μA
Collector-Base Cutoff Current	1	-	< -1	-50	nA	V <sub>CB</sub> = -36V
Collector-Base Cuton Current	I <sub>CBO</sub>	-	-	-20	μA	V <sub>CB</sub> = −36V, T <sub>amb</sub> = +100 °C
Emitter-Base Cutoff Current	I <sub>EBO</sub>	-	< -1	-50	nA	V <sub>EB</sub> = -5.6V
		300	450	900		$I_{C} = -10mA, V_{CE} = -2V$
Static Forward Current Transfer Ratio (Note 9)	h <sub>FE</sub>	120	200	-	-	I <sub>C</sub> = -1.5A, V <sub>CE</sub> = -2V
		15	40	-		$I_{C} = -3A, V_{CE} = -2V$
	V <sub>CE(sat)</sub>	-	-75	-95	mV	I <sub>C</sub> = -0.5A, I <sub>B</sub> = -20mA
		-	-200	-290		$I_{C} = -1A, I_{B} = -20mA$
Collector-Emitter Saturation Voltage (Note 9)		-	-95	-115		$I_{C} = -1A, I_{B} = -100mA$
		-	-160	-190		I <sub>C</sub> = -1.5A, I <sub>B</sub> = -75mA
		-	-245	-300		$I_{C} = -3A, I_{B} = -300mA$
Base-Emitter Saturation Voltage (Note 9)	V <sub>BE(sat)</sub>	-	-915	-1000	mV	$I_{C} = -1.5A, I_{B} = -75mA$
Base-Emitter Saturation Voltage (Note 9)	V <sub>BE(on)</sub>	-	-825	-900	mV	$I_{C} = -1.5A, V_{CE} = -2V$
Output Capacitance	C <sub>obo</sub>	-	17.4	25	рF	$V_{CB} = -10V$ , f = 1MHz
Transition Frequency	f⊤	-	270	-	MHz	V <sub>CE</sub> = -10V, I <sub>C</sub> = -50mA, f = 50MHz
Delay Time	t <sub>(d)</sub>	-	34	-	ns	
Rise Time	t <sub>(r)</sub>	-	41	-	ns	V <sub>CC</sub> = -15V, I <sub>C</sub> = -750mA,
Storage Time	t <sub>(s)</sub>	-	266	-	ns	$I_{B1} = -I_{B2} = -15mA$
Fall Time	t <sub>(f)</sub>	-	53	-	ns	7

Notes: 9. Measured under pulsed conditions. Pulse width  $\leq$  300 µs. Duty cycle  $\leq$  2%.



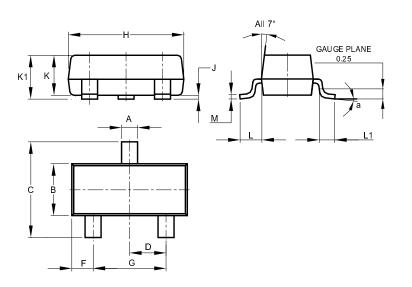
# Typical Electrical Characteristics (@T<sub>A</sub> = +25 °C, unless otherwise specified.)





# **Package Outline Dimensions**

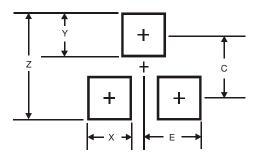
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
К	0.890	1.00	0.975		
K1	0.903	1.10	1.025		
L	0.45	0.61	0.55		
L1	0.25	0.55	0.40		
М	0.085	0.150	0.110		
а	8°				
All	All Dimensions in mm				

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
E	1.35



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